

09-12-2000



101453803

RECORDATION FORM COVER SHEET - PATENTS ONLY

9.7.00 MPO

To the Assistant Commissioner for Patents  
Please record the attached document thereof.

1. Name of conveying party(ies):

- (a) Huan-Chiu Tsen
- (b) \_\_\_\_\_
- (c) \_\_\_\_\_

Additional name(s) of conveying party(ies) attached? XXX  
Yes No

2. Name and address of receiving party:

Name: Winbond Electronics Corporation  
 Street \_\_\_\_\_  
 Address: No. 4 Creation Road III  
 City: Science-Based Inds. Park  
 State: Hsinchu, Taiwan  
 Zip Code: R.O.C.

3. Nature of conveyance:

- Assignment
- Security Agreement
- Other
- Merger
- Change of Name

Execution date: August 29, 2000

Additional name(s) and address(es) attached?

- Yes
- No

09/11/2000 A60ITOM 00000003 09585422

4. Application number(s) or patent number(s) FC:581 40.00 DP  
If this document is being filed together with a new application, the execution date of the application is \_\_\_\_\_

- (a) Patent Application No(s): 09/585,422
- (b) Patent No(s): \_\_\_\_\_
- (c) Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Finnegan, Henderson, Farabow, Garrett & Dunner, L.L.P.  
 Street \_\_\_\_\_  
 Address: 1300 I Street, N.W.  
 City: Washington  
 State: D.C. Zip Code: 20005

6. Total number of applications and/or patents involved: 1

7. Total Fee (37 C.F.R. § 3.41): \$40.00  
 Enclosed  
 Charge to Deposit Account No. 06-0916

8. Statement and signature:  
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Richard V. Burgujian  
 Name of person signing  
 Registration No. 31,744

Signature

9/6/00  
 Date

Total number of pages including all attachments? 2

SOLE/JOINT INVENTION  
(Worldwide Rights - Foreign Use)

Attorney Docket No.: 6484.0026

**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), hereinafter referred to as Assignor(s), have made an invention entitled MIXED PROGRAM AND SENSE ARCHITECTURE USING DUAL-STEP VOLTAGE SCHEME IN MULTI-LEVEL DATA STORAGE IN FLASH MEMORIES for which I/We filed an application for United States Letters Patent on June 2, 2000 (Serial No. 09/585,422); and

WHEREAS, Winbond Electronics Corporation, a corporation of Taiwan whose post office address is No. 4 Creation Road III, Science-Based Industrial Park, Hsinchu, Taiwan R.O.C. (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/We, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application to insert here in parentheses (Application No. 09/585,422, filed June 2, 2000) the filing date and application number of said application when known.

HUAN-CHIU TSEN  
FULL NAME OF SOLE OR FIRST INVENTOR

INVENTOR'S SIGNATURE

DATE

*Huan-chiu Tsen* 8/29/00